ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	Material Compo © Copyright 2005. IPG international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information				
Supplier Inform	nation						·							
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
onsemi											2024-05-01			
Contact Name			Title - Contact			P	Phone - Contact*				Email - Contact*			
Product-Env-Stew	ards	Product Enviro Compliance			ı	NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			P	Phone - Representative*				Email - Representative*			
Product-Env-Stewards Pr				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Request	Requester Item Number Mfr Iter		m Number Mfr Item Name				Effective Date	Version	ı	Manufacturing Site		Weight*	UOM	Unit Type
		NTBLS1	NTBLS1D5N08MC PTNG 80V		G 80V in TOLL for industrial market		2024-05-01 PBB		PBB	811.7391		mg	Each	
<b>Ianufacturing</b>	Proccess Informati	on				,							·	
Terminal Plating / Grid Array Material Te			erminal Base Alloy J-STD-020 MSL		-STD-020 MSL Rat	ing	Peak Process Body Temperature Max Time		re Max Time at Peak	Tempera	ture Numbe	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed		CU Alloy 1				260   C   30		30	seconds 3					
omments														
vel 1 - maximum	time at peak temperatur	e during sol	dering is 10-3	30 seconds										
or more informat	ion regarding material c	omposition ]	please refer t	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best in form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.35	mg	Supplier	Silicon (Si)	7440-21-3		6.35	mg
Die Attach Solder	7.6901	mg	Supplier	Silver (Ag)	7440-22-4		0.1923	mg
			A	Lead (Pb)	7439-92-1	7a	7.344	mg
			Supplier	Tin (Sn)	7440-31-5		0.1538	mg
Lead Frame	474.555		В	Nickel (Ni)	7440-02-0		0.2373	mg
			Supplier	Iron (Fe)	7439-89-6		0.4746	mg
			Supplier	Copper (Cu)	7440-50-8		473.7008	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1424	mg
Mold Compound-Black	314.85	mg		Proprietary	proprietary data		25.188	mg
			Supplier	Carbon Black (C)	1333-86-4		1.5742	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		288.0878	mg
Plating	8.12	mg	Supplier	Tin (Sn)	7440-31-5		8.12	mg
Wire Bond - Al	0.174	mg	Supplier	Aluminum (Al)	7429-90-5		0.174	mg